

# 0.8A, 50V - 1000V Fast Recovery Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

#### **MECHANICAL DATA**

Case: Sub SMA

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

• Polarity: Indicated by cathode band

• Weight: 0.019g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
l <sub>F</sub>	0.8	Α		
$V_{RRM}$	50 - 1000	V		
I <sub>FSM</sub>	30	Α		
$T_{JMAX}$	150	°C		
Package	Sub SMA			
Configuration	Single die			









Sub SMA



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)									
PARAMETER	SYMBOL	RS1 ALH	RS1 BLH	RS1 DLH	RS1 GLH	RS1 JLH	RS1 KLH	RS1 MLH	UNIT
Marking code on the device		RAL	RBL	RDL	RGL	RJL	RKL	RML	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Forward current	I <sub>F</sub>	0.8				Α			
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30				А			
Junction temperature	$T_J$	- 55 to +150				°C			
Storage temperature	T <sub>STG</sub>	- 55 to +150				°C			

1

Taiwan Semiconductor

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	32	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	105	°C/W	

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>		$I_F = 0.8A, T_J = 25^{\circ}C$	V <sub>F</sub>	-	1.3	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C	I <sub>R</sub>	-	5	μΑ
		T <sub>J</sub> = 125°C		-	50	μΑ
Junction capacitance		1MHz, V <sub>R</sub> = 4.0V	CJ	10	-	pF
RS1/ RS1I RS1I Reverse recovery time		IF = 0.5A, IR = 1.0A,	t <sub>rr</sub>	-	150	ns
Theverse recovery lime	RS1JLH	I <sub>rr</sub> = 0.25A	rr .	-	250	ns
	RS1KLH RS1MLH			-	500	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
RS1xLH	Sub SMA	10,000 / Tape & Reel		

## Notes:

1. "x" defines voltage from 50V(RS1ALH) to 1000V(RS1MLH)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

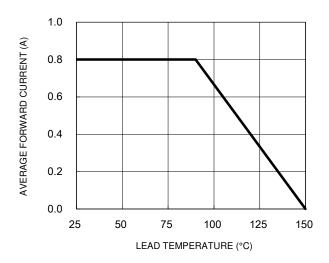


Fig.3 Typical Reverse Characteristics

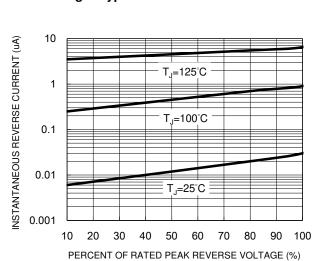


Fig.2 Typical Junction Capacitance

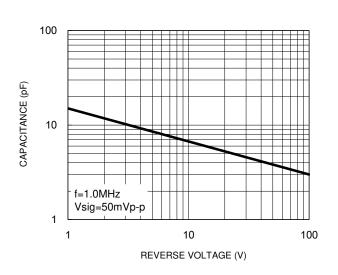


Fig.4 Typical Forward Characteristics

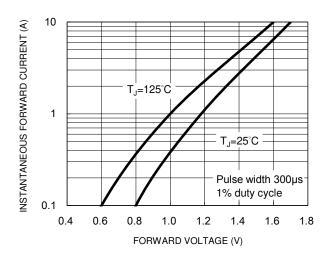
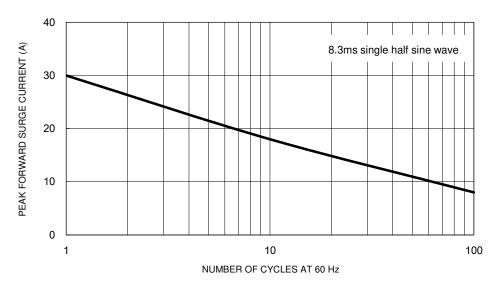


Fig.5 Maximum Non-Repetitive Forward Surge Current

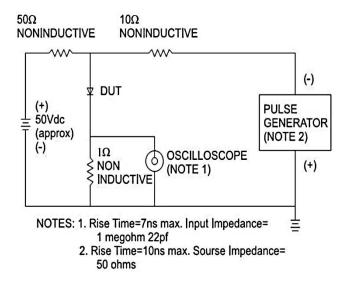


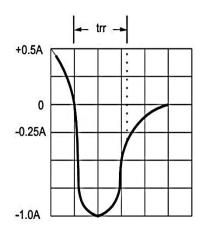
Taiwan Semiconductor

## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

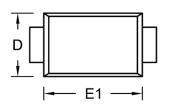


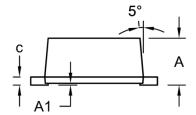


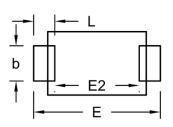


# **PACKAGE OUTLINE DIMENSIONS**

## Sub SMA

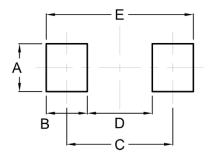






DIM. Unit		(mm)	Unit (	(inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	1.23	1.43	0.048	0.056
A1	0.00	0.10	0.000	0.004
b	0.80	1.20	0.031	0.047
С	0.16	0.30	0.006	0.012
D	1.70	1.90	0.067	0.075
E	3.40	3.80	0.134	0.150
E1	2.70	2.90	0.106	0.114
E2	2.45	2.60	0.096	0.102
L	0.35	0.85	0.014	0.033

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

# **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



Taiwan Semiconductor

#### **Notice**

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.